

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Chun Hung LIN

Serial No. 09/854,487

Filed: May 15, 2001

Group Art Unit: 2823

Examiner: D. Collins



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SEP 10 2002
TECHNOLOGY CENTER 280C

For: LOW-PIN-COUNT CHIP PACKAGE AND MANUFACTURING METHOD THEREOF

COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Dear Sir:

Transmitted herewith is an Amendment in the above identified application.

☒ No additional fee is required.☐ Small entity status of this application has been established.☐ A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is enclosed.☐ Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	16	20	0	x \$ 18 =	\$ 0.00
Independent Claims	2	3	0	x \$ 80 =	\$ 0.00
If multiple claims newly presented, add \$260.00					\$0.00
Fee for extension of time					\$0.00
TOTAL FEE DUE					\$ 0.00

☐ A check in the amount of \$0.00 is attached

☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 07-1337, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

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17. The chip package of claim 15, wherein said piece has a first portion embedded in the package body and a second portion located outside the package body, said second portion